

Title (en)
Gas shielded arc welding flux cored wire

Title (de)
Fülldraht zum Lichtbogenschweissen in Schutzgas

Title (fr)
Fil fourré pour le soudage à l'arc sous gaz protecteur

Publication
EP 0897774 A1 19990224 (EN)

Application
EP 98114344 A 19980730

Priority
JP 22650297 A 19970822

Abstract (en)
Realized is a welding wire containing flux used for a gas shielded arc welding of a direct current/positive polarity mode, with use of which a quantity of sputter generated is small, a good weldability is realized and a weld metal with an excellent toughness is obtained in all the welding positions under application of a welding current in the range of a low current to a medium current, or in a definite manner in the range of 50 to 300 A. The flux contains 0.7 to 3 wt % Al, 0.1 to 1.0 wt % Mg and 1.2 to 5 wt % BaF₂, each content being a value in wt % to a total weight of the wire and the sum of a content of Al plus a content of Mg multiplied by 3 being in the range of 1.3 to 5 wt %, a filling ratio of the flux to the total weight of the wire is in the range of 5 to 30 wt %, a total Mn content in a steel sheath and the flux combined is in the range of 0.2 to 1.9 wt % and a total Si content in the steel sheath and the flux combined is in the range of 0.001 to 0.9 wt %. <IMAGE>

IPC 1-7
B23K 35/368

IPC 8 full level
B23K 35/36 (2006.01); **B23K 35/368** (2006.01)

CPC (source: EP US)
B23K 35/3605 (2013.01 - EP US); **B23K 35/368** (2013.01 - EP US)

Citation (search report)

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- [A] US 4571480 A 19860218 - SAKAI YOSHIYA [JP], et al
- [A] FR 2270982 A1 19751212 - LINCOLN ELECTRIC CO [US]
- [AD] PATENT ABSTRACTS OF JAPAN vol. 014, no. 224 (M - 0972) 11 May 1990 (1990-05-11)

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